

October 22, 2025

**(Progress of a Disclosed Item) Notice of the Start of Transaction of Shares of
Our Equity-method Affiliate (Semiconductor Wafer Business)
in the “New Third Board” (OTC Market) in China**

As the progress of a disclosed matter, Ferrotec Corporation (Representative Director: He Xian Han; hereinafter “the Company”) announces that the registration of shares of Hangzhou Semiconductor Wafer Co., Ltd. (hereinafter “CCMC”), which is an equity-method affiliate of the Company and manufactures semiconductor wafers, in the National Equities Exchange and Quotations (hereinafter “the New Third Board”), which is an over-the-counter market in China, was approved and it was disclosed in China on October 21, 2025 that CCMC’s shares will be tradable on the New Third Board from October 22, 2025.

1. Situation of the registration on the New Third Board

(1)	Abbreviation of the securities	CCMC
(2)	Securities code	874810
(3)	Date of start of over-the-counter trading	October 22, 2025

2. Overview of CCMC as of August 31, 2025

(1)	Name	Hangzhou Semiconductor Wafer Co., Ltd. (CCMC)	
(2)	Address	No. 888 Dongken Road, Qiantang New District, Hangzhou, Zhejiang, Peoples Republic of China	
(3)	Title and name of representative	He Xian Han, Legal representative	
(4)	Contents of business	Manufacture and sale of semiconductor wafers	
(5)	Capital	5,032 million yuan (approx. 106.6 billion yen) (1 Chinese yuan = 21.19 yen)	
(6)	Date of establishment	September 28, 2017	
(7)	Our shareholding ratio	23.05%	
(8)	Relationship between CCMC and the Company	Capital relationship	CCMC is an equity-method affiliate of the Company.
		Personnel relationship	One Director of the Company concurrently serves as the Representative Director of CCMC.
		Business relationship	None applicable

3. Future outlook and prospects

The impact on the consolidated business performance of the Group for the current fiscal year is expected to be minor at the time of releasing this document. However, we will promptly disclose relevant items as soon as they are confirmed.

4. Note

Please also refer to the following materials for this matter.

Release date	Title
October 22, 2025	Notice of the (Third) Issuance of New Shares through Third-Party Allotment by Our Equity-method Affiliate (Semiconductor Wafer Business)
September 24, 2025	(Progress of a Disclosed Item) Notice of the Approval of an Application for Listing on the “New Third Board” (OTC Market) in China Submitted by Our Equity-method Affiliate (Semiconductor Wafer Business)
July 3, 2025	Notice of the Acceptance of Application for Listing on the “New Third Board” (OTC Market) in China Submitted by Our Equity-method Affiliate (Semiconductor Wafer Business)
July 4, 2024	Notice of the Withdrawal of a Listing Application by Our Equity-Method Affiliate (Semiconductor Wafers)

August 30, 2022	Notice of an Application for Listing on the Science and Technology Innovation Board of the Shanghai Stock Exchange by a Semiconductor Wafer Equity-Method Affiliate
October 20, 2021	Notice of the Conclusion of an Advisory Contract for Listing Between Our Equity-Method Affiliate (Semiconductor Wafer Business) and Haitong Securities Co. Ltd. (Managing Underwriter) and the Approval for Registration by the China Securities Regulatory Commission
September 15, 2021	Notice of the Completion of Payment of the (Second) Issuance of New Shares through Third-Party Allotment at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers
September 15, 2021	(Correction and Change of a Disclosed Item) Notice of the (Second) Issuance of New Shares through Third-Party Allotment and Capital Investment (Acquisition of Fixed Assets) at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers
July 15, 2021	(Change of a Disclosed Item) Notice of the (Second) Issuance of New Shares through Third-Party Allotment and Capital Investment (Acquisition of Fixed Assets) at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers
June 30, 2021	(Correction of a Disclosed Item) Notice of Listing of an Equity-Method Affiliate That Manufactures Semiconductor Wafers
June 29, 2021	Notice of Listing of an Equity-Method Affiliate That Manufactures Semiconductor Wafers
April 15, 2021	Notice of the (Second) Issuance of New Shares through Third-Party Allotment and Capital Investment (Acquisition of Fixed Assets) at an Equity-Method Affiliate for Manufacturing Semiconductor Wafers
February 10, 2021	Notice of Change of Specific Subsidiaries that Manufacture Semiconductor Wafers
November 13, 2020	(Addition/Correction of a Disclosed Item) Notice of the Issuance of New Shares through Third-Party Allotment by the Subsidiary that Manufactures Semiconductor Wafer
November 13, 2020	(Correction of a Disclosed Item) Notice of the Completion of Payment for New Shares through Third-Party Allotment by the Subsidiary that Manufactures Semiconductor Silicon Wafers
November 5, 2020	(Correction of a Disclosed Item) Notice of the Completion of Payment of the Price for Transfer of Shares of the Subsidiary that Manufactures Semiconductor Silicon Wafers
November 2, 2020	(Progress of a Disclosed Item) Notice of the Completion of Payment for New Shares through Third-Party Allotment by the Subsidiary that Manufactures Semiconductor Wafer
October 19, 2020	(Progress of a Disclosed Item) Notice of the Completion of Payment of the Price for Transfer of Shares of the Subsidiary that Manufactures Semiconductor Silicon Wafers
October 16, 2020	Notice of the Issuance of New Shares through Third-Party Allotment by the Subsidiary that Manufactures Semiconductor Wafer
September 17, 2020	(Addition/Revision of Contents) Notice of Transfer of Some Shares of the Subsidiary that Manufactures Semiconductor Wafers
September 15, 2020	Notice of Transfer of Some Shares of the Subsidiary that Manufactures Semiconductor Wafers

This document is a disclosure for public announcement in relation to preparations to reorganize our consolidated subsidiary called Ferrotec (Anhui) Technology Development Co., Ltd. We did not prepare this document to solicit any kind of investment or for any similar activities. In addition, no part of this document should form or be relied on as the basis of contracts, promises or investment decisions relating to China, Japan, the United States and other regions. Accordingly, this document does not constitute or intend to be an offer for or a solicitation to acquire stocks or securities in any jurisdiction including the United States. It is not possible to offer and sell securities without registration or exemption from registration in the United States. The purchase of securities through public offering should be done based only on information included in the final offering memorandum or prospectus relating to those securities. Our subsidiary does not intend to make a public offering of securities in the United States at the present time.